



Product/Process Change Notice - PCN 14_0071 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

PCN Title: Addition of STATS ChipPAC China as an Alternate Assembly Site for Select 3x3mm LFCSP Products

Publication Date: 03-Apr-2014

Effectivity Date: 02-Jul-2014 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release

Description Of Change

ADI is in process of qualifying subcontractor STATS ChipPAC China for the assembly manufacturing of ADI products in 3x3mm LFCSP packages. The package outline dimensions will be maintained.

For BOM changes see below.

Die Attach Epoxy:

From:LOCTITE QMI519

To:Ablestik 8290

Mold Compound

From:Sumitomo G770HC

To:Sumitomo G770

Reason For Change

The use of ADI qualified STATS ChipPAC China as an additional assembly site for this package will ensure continued source of product supply. ADI's assembly subcontractors manufacture our products using Analog Devices specified manufacturing flows, process controls and monitors. This assures that our customers receive the same level of quality and reliability on products they receive from qualified ADI manufacturing locations.

Impact of the change (positive or negative) on fit, form, function & reliability

Utilization of additional subcontractor allows future shipments of affected material from either site. The device fit, form, function, and reliability, as specified by Product Data Sheets, will not be affected by this change.

Product Identification *(this section will describe how to identify the changed material)*

The parts assembled in STATS ChipPAC China, will be identified with China as the Country of Origin.

Summary of Supporting Information

Qualification will be performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Plan Summary.

Supporting Documents

Attachment 1: Type: Qualification Plan Summary

ADI_PCN_14_0071_Rev_-_Reliability Qualification Plan.pdf

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative

Americas: PCN_Americas@analog.com

Europe: PCN_Europe@analog.com

Japan: PCN_Japan@analog.com

Rest of Asia: PCN_ROA@analog.com

Appendix A - Affected ADI Models**Added Parts On This Revision - Product Family / Model Number (27)**

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|-----------------------------|----------------------------|-----------------------------|-----------------------------|-----------------------------|
| AD7683 / AD7683ACPZRL | AD7683 / AD7683ACPZRL7 | AD7683 / AD7683BCPZRL | AD7683 / AD7683BCPZRL7 | AD7980 / AD7980ACPZ-RL |
| AD7980 / AD7980ACPZ-RL7 | AD7980 / AD7980BCPZ-R2 | AD7980 / AD7980BCPZ-RL | AD7980 / AD7980BCPZ-RL7 | AD7982 / AD7982BCPZ-RL |
| AD7982 / AD7982BCPZ-RL7 | AD7983 / AD7983BCPZ-R2 | AD7983 / AD7983BCPZ-RL | AD7983 / AD7983BCPZ-RL7 | AD7984 / AD7984BCPZ-R2 |
| AD7984 / AD7984BCPZ-RL | AD7984 / AD7984BCPZ-RL7 | AD7988-1 / AD7988-1BCPZ-RL | AD7988-1 / AD7988-1BCPZ-RL7 | AD7988-5 / AD7988-5BCPZ-RL |
| AD7988-5 / AD7988-5BCPZ-RL7 | AD7989-1 / AD7989-1BCPZ-R2 | AD7989-1 / AD7989-1BCPZ-RL7 | AD7989-5 / AD7989-5BCPZ-R2 | AD7989-5 / AD7989-5BCPZ-RL7 |
| PCV-DUMP / AD7989-1BCPZ-RL | PCV-DUMP / AD7989-5BCPZ-RL | | | |

Appendix B - Revision History

| Rev | Publish Date | Effectivity Date | Rev Description |
|------------|---------------------|-------------------------|------------------------|
| Rev. - | 03-Apr-2014 | 02-Jul-2014 | Initial Release |
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Analog Devices, Inc.

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